



Standard Assembly Build Sheet (Air Cavity - OmPP, OcPP, Ceramic, etc.)

Original request

Changed request

Rev # _____

QP Internal S.O. #: _____

QP Quote #: _____

QP Sales Contact: _____

CUSTOMER CONTACT INFORMATION

Company: _____

Contact Name: _____ Date: _____

Phone: _____

Email: _____

P.O. #: _____

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)? Yes No

DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY. STANDARD LEAD TIME FOR BENCHMARK ORDER (PKG: OmPP, PKG QTY: <100, WIRE COUNT: <50, SINGLE DIE ATTACH) IS 3 DAYS. EXPEDITE (1-2 DAYS). PREMIUM (8 HRS).

Standard

Expedite

Premium

DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPARATELY.

Die Format: Waffle Pack Gel-Pak Diced Wafer on Tape Wafer (requires processing) Other: _____

Die Size: _____ X _____ μ m or mils

(a) Wafer ID/Die ID:

(b) Lot #

(c) Qty of Devices to be Assembled from ID

Pad Pitch: _____ X _____ μ m or mils Bond

1a. _____

1b. _____

1c. _____

Pad Dims: _____ X _____ μ m or mils Bond

2a. _____

2b. _____

2c. _____

Pad Opening: _____ X _____ μ m or mils

3a. _____

3b. _____

3c. _____

Thickness: _____ μ m or mils

4a. _____

4b. _____

4c. _____

Metalization: Aluminum Gold Other (Specify): _____

Probed?

Passivated?

DEVICE INFORMATION

Device Name: _____ Pin Count: _____ Lead Pitch: _____ Die Per Package: _____ Wire Count Per Package: _____

Qty of Devices to be Assembled: _____ Body Size (mm): _____ X _____

Packages provided by: Customer Quik-Pak Packages Require Opening (OcPP)

Package Type: OmPP (QFN/SOIC) Ceramic Other: _____

Package Description: _____

SPECIAL INSTRUCTIONS (ATTACH ADDITIONAL DOCUMENTS IF NEEDED)

CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFMs THAT WILL BE SHIPPED TO QUIK-PAK. IF MORE SPACE IS NEEDED, ATTACH ADDITIONAL DOCUMENTS.

1. _____ 2. _____ 3. _____

4. _____ 5. _____ 6. _____

7. _____ 8. _____ 9. _____

ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A BONDING DIAGRAM BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION, AND WIRES BONDS.

Please Indicate The File Format: CAD Drawing Other (JPEG, PowerPoint, PDF, etc.)

Select Die From: Center of Wafer(s) Wafer Map(s) Reticle Map-include with Build Sheet

Die Attach Material (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT MATERIALS):

____ Conductive Epoxy ____ High Thermally Conductive/Electrically Non-Conductive
____ Non-Conductive Epoxy ____ High Thermally Conductive/Electrically Conductive Material

Gold Wire Diameter (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT WIRE DIAMETER):

*STANDARD MATERIAL. OTHER OPTIONS MAY INCREASE COST/LEADTIME.

____ 0.7 mil ____ 0.8 mil ____ 1.0 mil* ____ 1.2 mil
____ 1.3 mil ____ 1.5 mil ____ 2.0 mil ____ Other (AI available - call for wire size)

Die to Die Bond Lead to Down Bond (or jumper wire) Lead to Lead Bond

Gold Ribbon: ____ 1 X 2 mil ____ 1 X 3 mil ____ 1 X 4 mil

Lead Trim? Yes No Requested Lead Length: _____ mil

Seal (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT SEALING METHODS):

____ None ____ Encapsulation Around Leads Only Removable Lid (For Walled Packages):
____ Standard Full Encapsulation (Glop Top) ____ Frame & Lid (For Non-Solder Applications) ____ Epoxy on 4 Corners
____ Remolded / Flattened (Jedec std.) ____ Solder Sealed Lids ____ Epoxy on 2 Corners
____ Clear encapsulant (UV Cure) ____ Epoxy Seal Lid ____ Taped on Lids
____ Other (Specify) _____

Marking (MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COSTS.):

Hand Mark pin 1 on device?

Custom Design

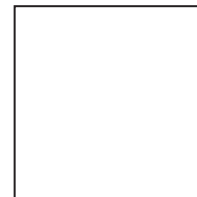
No Custom Marking

Hand Mark (Max. 1-3 characters): _____

Pad Print (White on Black) - E-mail artwork in native .EPS or .AI file format

Laser Mark (Black on Black) - E-mail artwork in native .EPS or .AI file format

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:



Please mark pin 1 corner and indicate how marking should appear on package relative to pin 1.

SHIPPING (Contact QP with any special requests)

Reject Parts Disposition: Return to Customer Bag and Tag Destroy

*Unless otherwise noted all extra materials will be returned.

Shipping Method (Please Select) Account #: _____

Pickup FedEx DHL UPS Courier Special Instructions

Ship To Address (Finished Product):

Attn: _____

Address: _____

Ship To Address (Excess Die and Materials):

Attn: _____

Address: _____

Include Certificate of Conformance

Ship Materials In

Trays

Tubes

Other: _____

Containers Provided

Quik-Pak

Customer

For Quik-Pak Internal Use Only:

Orders meeting one of the following requirements require signatures by representatives in the following departments:

☐ Over \$20k ☐ ISO-13485 Processing ☐ Change in instructions after order has been released to production

Sales: _____ Date: _____

Engineering: _____ Date: _____

Manufacturing: _____ Date: _____

QA: _____ Date: _____

Per Quik-Pak quality program, risk assessment is required on orders over \$100k and/or Medical orders built under ISO-13485 std.